

The background of the advertisement features a series of industrial robotic arms, likely from the Vincotech brand, arranged in a perspective view that recedes into the distance. The arms are white and black, with visible joints and grippers. They are positioned over a dark, reflective surface, possibly a conveyor belt or a polished floor. The lighting is bright and even, highlighting the metallic textures of the robots. A large, dark, diagonal shape cuts across the left side of the image, serving as a backdrop for the main text.

MORE CHOICES, GREATER SECURITY

flow E1/E2 with IGBT M7
for low-power motion control



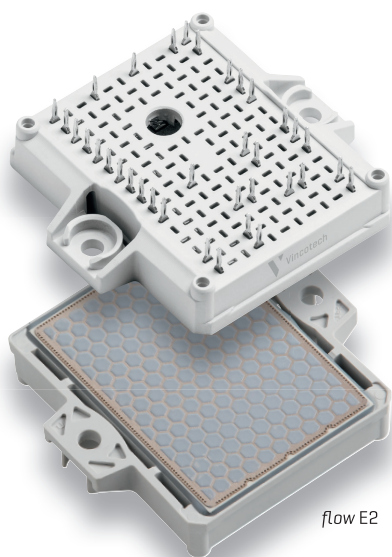
Vincotech

EMPOWERING YOUR IDEAS

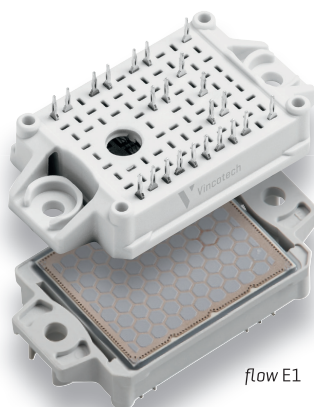
FEWER SUPPLY CHAIN ISSUES, TOP PERFORMANCE

New *flow*PIM & *flow*PACK E1/E2 with IGBT M7

Every business wants a more reliable supply chain. And in our line of business, it takes a multi-sourcing strategy to make that happen; a policy that factors both mechanical and electrical components into the design. Vincotech covers both with the *flow*E standard industry package for low-power motor drive applications. Rounding out our range, *flow* E1/E2 ships with IGBT M7 chip technology.



flow E2



flow E1

Vincotech 1200 V *flow* E IGBT4 vs. IGBT M7

Discover the new PIM [CIB] and sixpack configurations with power ranges extending up to 50 A and 100 A, respectively.

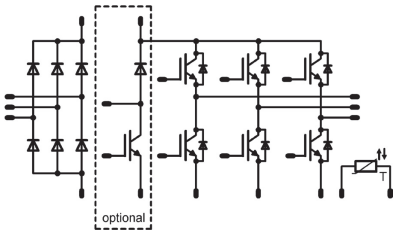
Topology	Package	Technology	I _{Cnom} [A]						
			10	15	25	35	50	75	100
PIM [CIB]	flow E1	IGBT4							
		IGBT M7			◆				
	flow E2	IGBT4							
		IGBT M7					◆		
SIXPACK	flow E1	IGBT4							
		IGBT M7					◆		
	flow E2	IGBT4							
		IGBT M7							◆

◆ Power Extension

More choices, greater security – that is Vincotech’s answer to customer demands for a more reliable supply chain. The new *flow* E IGBT M7 affords customer’s freedom of choice with real multi-sourcing options at every mechanical and electrical level.

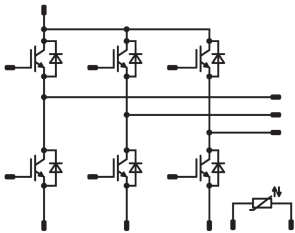
*flow*PIM E1/E2

For the full range of products, please visit www.vincotech.com/flowPIM-E



*flow*PACK E1/E2

For the full range of products, please visit www.vincotech.com/flowPACK-E



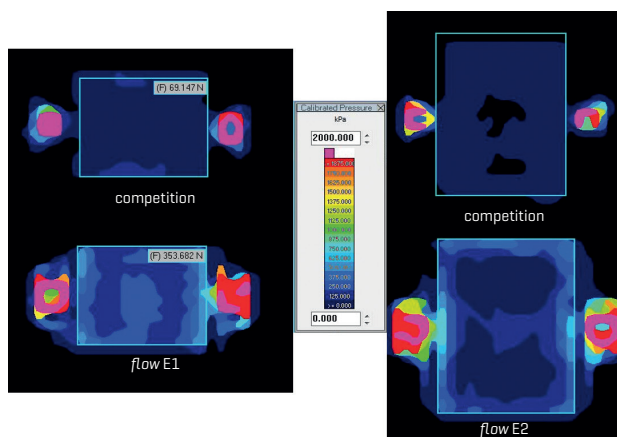
Key features

- / Fully compatible housing
- / Same PCB specification for Press-fit and solder pins
- / Same pin-out as standard topologies
- / Full product line for standard topologies (CIB, sixpack)

Key hardware features

- / 12 mm, low-inductive standard industrial package
- / Pre-bent DCB for excellent thermal contact to heat sink
- / CTI 600 housing material
- / Press-fit pins with stress-relieved zone
- / Optional phase-change material

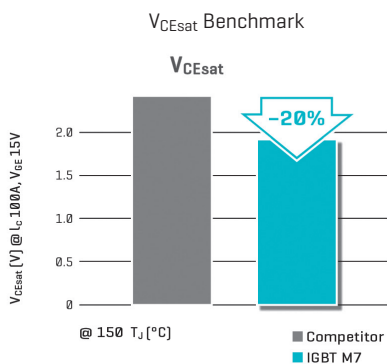
Pressure distribution benchmark for flow E1/ flow E2 and the competition



THE *flow E* MODULES
THERMAL CONTACT
TO THE HEAT SINK
IS MUCH BETTER,
RESULTING IN
LOWER $R_{th[J-S]}$

Key electrical features IGBT M7

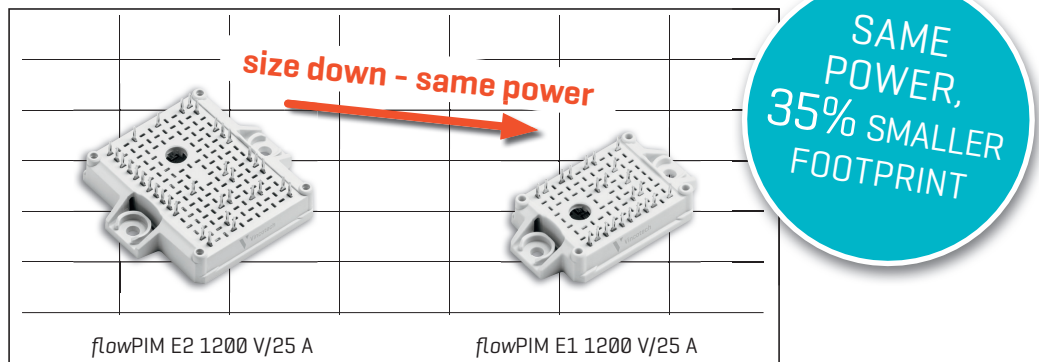
- / Lowest on-stage voltage V_{CEsat}
- / Optimized dynamic losses
- / Improved FWD softness
- / Enhanced dV/dt control



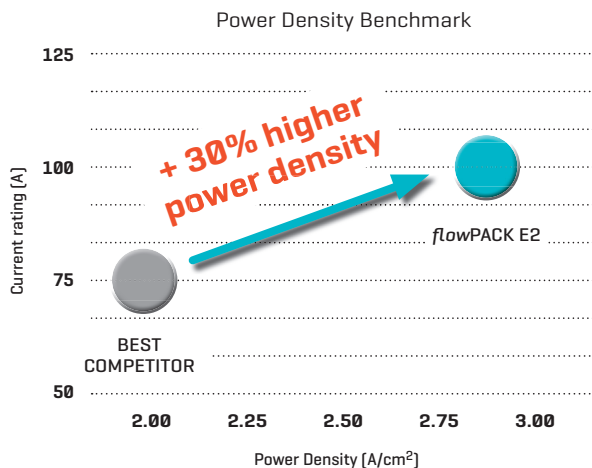
Customer benefits

- / Greater reliability, better thermal performance with 15% lower R_{th} than competing products
- / Higher power density in a smaller package or more power from the same package
- / Low losses to meet discriminating demands for high efficiency
- / Lower system costs

With *flow* E featuring 1200 V, a maximum current rating of 25 A can be realized in a smaller *flow* E1 housing. Thus, the same power can be achieved in a 35% smaller package for a more compact inverter design.



With the *flow* E2 package, a 30% higher power density can be achieved by increasing the maximum current from 75 A up to 100 A.





Vincotech

Vincotech GmbH

Biberger Strasse 93 / 82008 Unterhaching / Germany

T +49 89 878 067-0 / F +49 89 878 067-300

www.vincotech.com